



ST18N10D

N Channel Enhancement Mode MOSFET



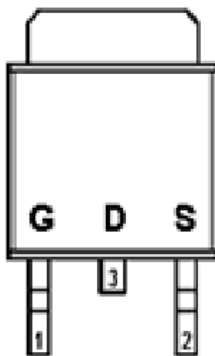
18.0A

DESCRIPTION

ST18N10D is the N-Channel logic enhancement mode power field effect transistor which is produced using high cell density, DMOS trench technology. The ST18N10D has been designed specially to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $R_{DS(ON)}$ and fast switching speed.

PIN CONFIGURATION (D-PAK)

TO-252



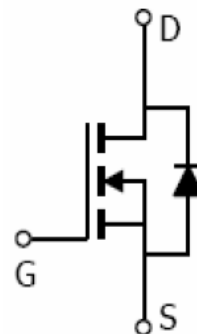
FEATURE

- 100V/12.0A, $R_{DS(ON)} = 90m\Omega$ (Typ.) @ $V_{GS} = 10V$
- 100V/8.0A, $R_{DS(ON)} = 100m\Omega$ @ $V_{GS} = 4.0V$

Super high density cell design for extremely low $R_{DS(ON)}$

- Exceptional on-resistance and maximum DC current capability
- TO-252 Package design

PART MARKING



W: Wafer Code P: Product Code
Y: Year Code A: Produce Code

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ABSOLUTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	VDSS	100	V
Gate-Source Voltage	VGSS	±20	V
Continuous Drain Current (TJ=150°C)	ID	18.0 12.0	A
Pulsed Drain Current	IDM	65	A
Continuous Source Current (Diode Conduction)	IS	16	A
Power Dissipation	PD	79	W
Operation Junction Temperature	TJ	150	°C
Storage Temperature Range	TSTG	-55/150	°C
Thermal Resistance-Junction to Ambient	RθJA	110	°C/W



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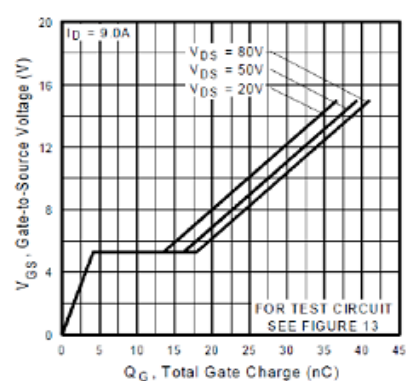
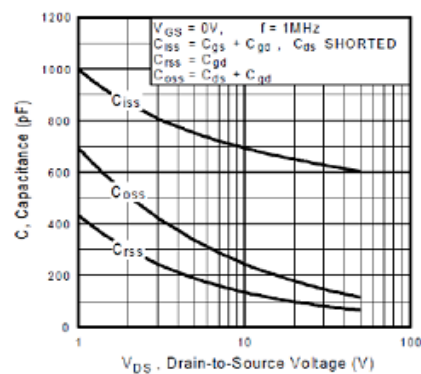
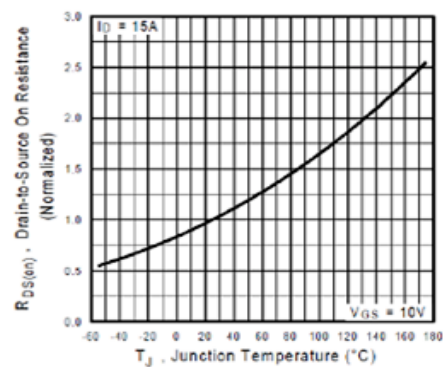
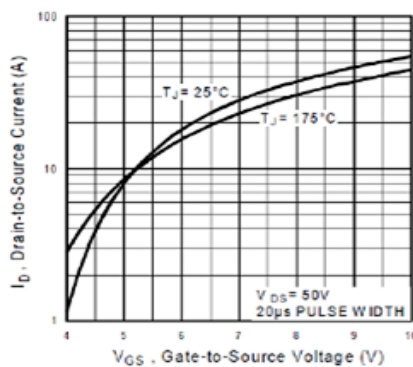
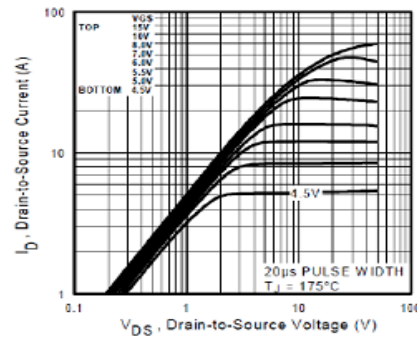
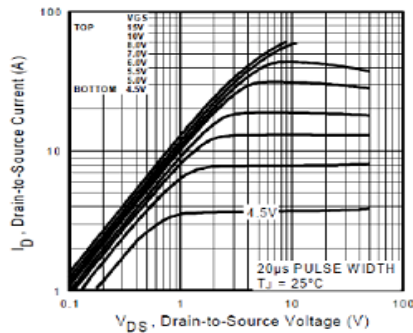


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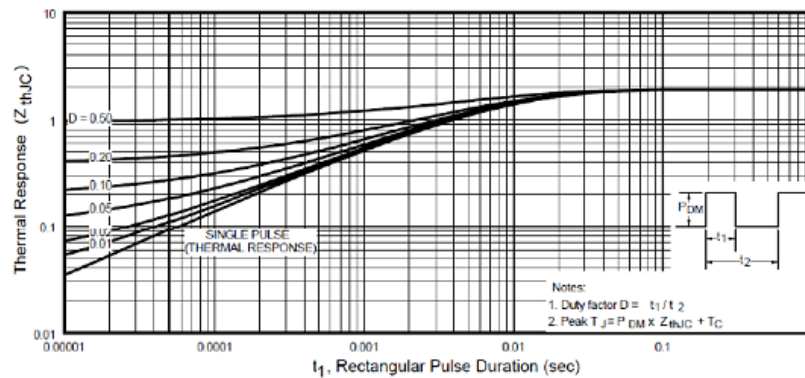
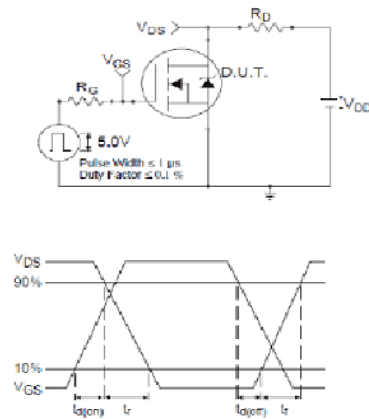
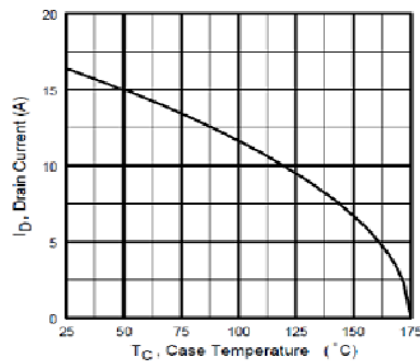
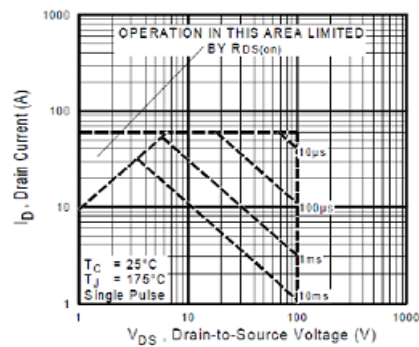
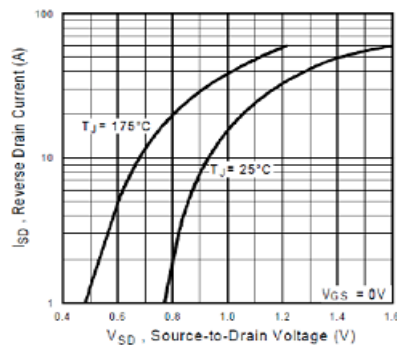
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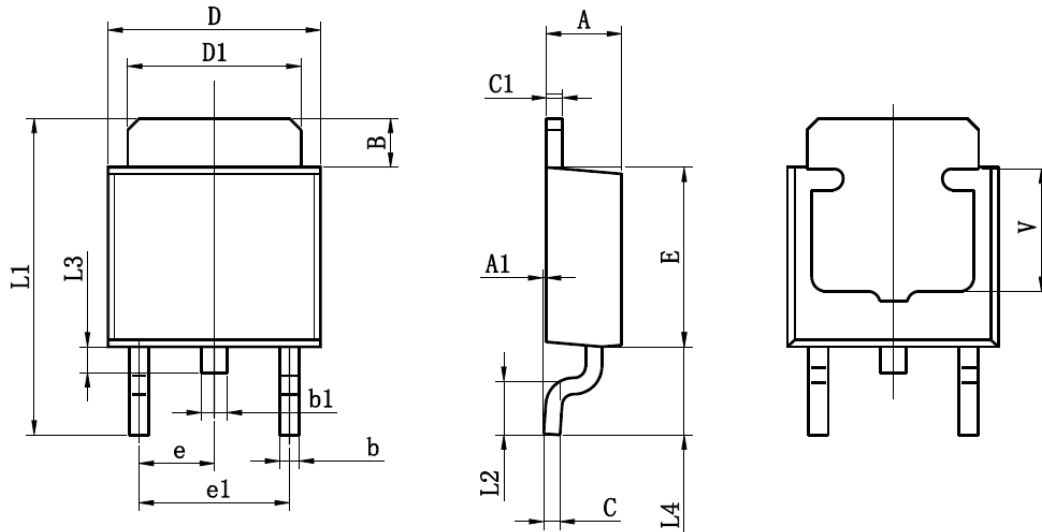
ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250mA	100			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.0		2.5	V
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V, V _{GS} =0V			12	uA
		V _{DS} =80V, V _{GS} =0V T _J =150℃			5	
Drain-source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =12A V _{GS} =4.5V, I _D =4.0A		90 95	100 120	mΩ
Forward Transconductance	g _{fs}	V _{DS} =50V, I _D =9.0A	6.4			S
Diode Forward Voltage	V _{SD}	I _S =9.0A, V _{GS} =0V			1.1	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =80V, V _{GS} =10V I _D =9.0A			45	nC
Gate-Source Charge	Q _{gs}				7.2	
Gate-Drain Charge	Q _{gd}				22	
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V F=1MHz		640		pF
Output Capacitance	C _{oss}			160		
Reverse TransferCapacitance	C _{rss}			88		
Turn-On Time	t _{d(on)} tr	V _{DD} =50V, R _D = 5.5Ω I _D =9.0A, V _{GEN} =10V R _G =12Ω		7.4		nS
Turn-Off Time	t _{d(off)} tf			29		
				40		
				25		

TYPICAL CHARACTERISTICS


TYPICAL CHARACTERISTICS



TO-252-2L PACKAGE OUTLINE SOP-8P


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300TYP		0.091TYP	
e1	4.500	4.700	0.177	0.185
L1	9.500	9.900	0.374	0.390
L2	1.400	1.780	0.055	0.070
L3	0.650	0.950	0.026	0.037
L4	2.550	2.900	0.100	0.114
V	3.80REF		0.150REF	